505875033 01/22/2020

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5921862

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:		
CONVEYING PARTY DATA		
	Name	Execution Date
ZHENKUI MENG		12/09/2019
ZHENGYAN LIU		12/09/2019

RECEIVING PARTY DATA

Name:	AAC ACOUSTIC TECHNOLOGIES (SHENZHEN) CO., LTD.
Street Address:	A-BLOCK, NO.6 YUEXING 3RD ROAD,SOUTH HI-TECH INDUSTRIAL PARK, NANSHAN DISTRICT
City:	SHENZHEN, GUANGDONG
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16708427

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email:	mail@uni-intel.com
Correspondent Name:	MICHAEL WIERSCH
Address Line 1:	3750 PEACOCK CT #3
Address Line 4:	SANTA CLARA, CALIFORNIA 95051

ATTORNEY DOCKET NUMBER:	2018A1273US1									
NAME OF SUBMITTER:	MICHAEL P. WIERSCH									
SIGNATURE:	/Michael P. Wiersch #55996/									
DATE SIGNED:	01/22/2020									
Total Attachments: 3										
source=2018A1273US1-Assignment#page1.tif										
source=2018A1273US1-Assignment#page2.tif										

source=2018A1273US1-Assignment#page3.tif

ASSIGNMENT

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

Method for Manufacturing MEMS Microphone

WHEREAS, <u>AAC Acoustic Technologies (Shenzhen) Co., Ltd.</u> a corporation of <u>China</u> whose post office address is <u>A-Block, Nanling University Research Center Shenzhen Branch, No. 6 Yuexing 3rd</u> <u>Road, South Hi-Tech Industrial Park, Nanshan District, Shenzhen, P. R. China 518057</u> (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

PATENT REEL: 051576 FRAME: 0597

Attorney Docket No.: 2018A1273US1

US Rights Page 2

Inventor:

Name: Zhenkui Meng Address: A-Block, Nanjing University Research Center Shenzhen Branch,No.6 Yuexing 3rd Road, South Hi-tech Industrial Park, Nanshan District,Shenzhen,518057 P.R.China

			un																				
D																							
								1															

PATENT REEL: 051576 FRAME: 0598 Attorney Docket No.: 2018A1273US1

US Rights Page 3

Inventor:

Name: Zhengyan Liu Address: A-Block, Nanjing University Research Center Shenzhen Branch,No.6 Yuexing 3rd Road, South Hi-tech Industrial Park, Nanshan District,Shenzhen,518057 P.R.China Signature: Zhengyan Liu

12.9

101

Date:

RECORDED: 01/22/2020

PATENT REEL: 051576 FRAME: 0599

3